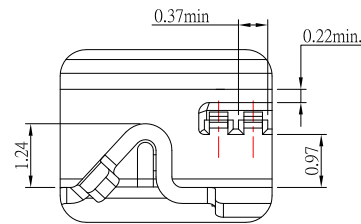
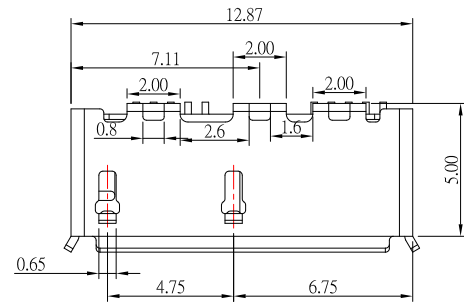




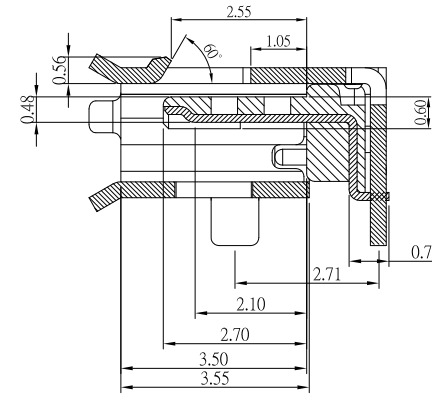
# MRUSB-10BD1B-30x-S277

鍍層厚度:

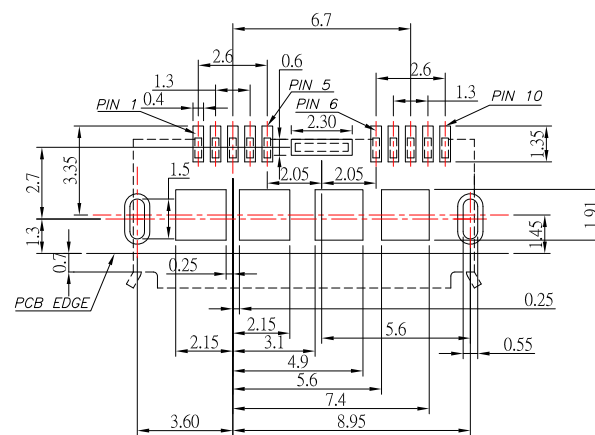
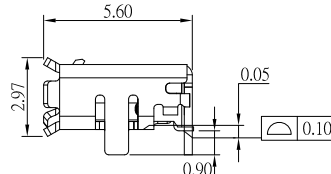
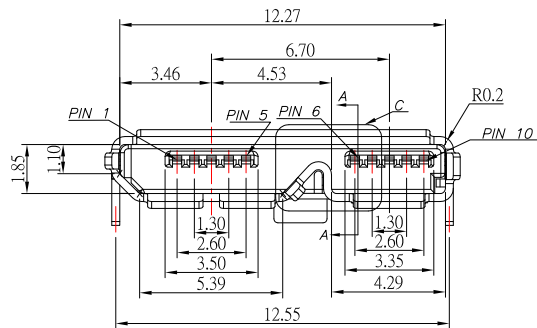
Blank : 1u"
2 : 15u"
3 : 30u"



Detail C (2:1)



SECTION "A-A" (2:1)



P.C.B LAYOUT MOUNTING PATTERN

Pin Number	Signal Name
1	VBUS Power
2	D-
3	D+
4	ID
5	GND
6	MicB_SSTX-
7	MicB_SSTX+
8	GND_DRAIN
9	MicB_SSRX-
10	MicB_SSRX+

NOTE:

1.MATERIAL:

- 1.1 INSULATOR: LCP, UL 94V-0,Black
- 1.2 CONTACT: BRASS
- 1.3 SHELL: SUS304

2.Finish:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;  
TIN PLATED ON SOLDER BALLS ;  
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER



东莞市高迪电子有限公司  
Dong Guan KDRR Electronic Switch Jack Co., Ltd.

TOLERANCE UNLESS OTHERWISE STATED

Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	03/18/15			
CHECKED BY:	DATE	FINISH	MODLE	MICRO 3.0 B/F DIPX3 , 腳長:0.9mm
Jacky Chen	03/18/15			
APPROVED BY:	DATE	SCALE	DWG NO.	MRUSB-10BD1B-30x-S277
Tony Kao	03/18/15	1 : 1	PART NO.	MRUSB-10BD1B-30x-S277
		SHEET NO.	1 of 1	
				SIZE A4
				VER R3

ITEM NO.	DESCRIPTION	DRAWN	DATE
3	新增pcb layout尺寸及更新外殼腳距離尺寸	Jack	031815
2	新增pin定義及新增尺寸	Jack	031715
1	新增pin定義	Jack	031315